Offline analysis for the beam test of CEPC vertex detector prototype

CEP Shuqi Li (IHEP, shuqi.li@cern.ch) The 2023 International Workshop on the High Energy Circular Electron Positron Collider Introduction > CEPC? > CMOS pixel sensor prototypes? Circular Electron Positron Collider^[1] proposed by Chinese TaiChuPix3 pixel sensor developed for the vertex detector particle physics community 1024 x 512 Pixel array 25um x 25 μ m per pixel \rightarrow high spatial resolution Double-ring collider with **electron and positron** beams circulated in opposite directions in separate beam pipes Process: CIS 180nm process modified process: Precise measurement of properties of Higgs, W and Z bosons Standard process (baseline option) faster charge collection Modified process^[2] (an extra low dose n-type layer) > Vertex detector ? 15.9 mm $H \rightarrow bb$ precise vertex High spatial resolution $(3 \sim 5 \mu m)$ reconstruction Radiation hard (>1Mrad) $H \rightarrow uu \text{ precise momentum}$ measurement Beam test @ DESY Test beam on pixel sensor prototype > DESY TB21 beam line [3] TEST BEAM Setup 6 equally spaced (4cm) detector module with TaichuPix3 • 4 ~ 6 GeV electron beam T24 T24/1 DUTA: modified process Hitmap of one DUT > Offline data analysis flow DUTB: standard process DESY II **Event** building DAQ \implies Raw data \implies Decoding Track fitting Clustering Alignment vents Clustering: geometric center of the Spatial resolution gravity of the neighboring fired pixels Estimation of intrinsic resolution^[6] Alianment: Millipede^[4] r_b: biased residual r_{h} $pull_b \equiv p_b = \sigma_{int}$: intrinsic resolution Track fitting: Straight line fit and $\sigma_{int}^2 - \sigma_{t,b}^2$; biased track uncertainty General broken line fit^[5] Test beam on vertex detector prototype **Resolution vs. Threshold** Mechanical prototype assembly Higher threshold \rightarrow less Doubled ladder with 2 TaichuPix3 chips on each side 1111 14 cluster size \rightarrow less charge sharing effects \rightarrow worse 6 ladders mounted on the mechanical prototype spatial resolution > Detection efficiency Beam test setup 2.5×2.5 m²) focus The detection efficiency Hitmap of one ladder on one side for both process can reach 99% at the lowest threshold **Cluster size** Conclusions The DUT with the standard luster : process shows more charge The spatial resolution of TaichuPix3 sensors can be $< 5 \mu m$ for both sharing effects processes The detection efficiency is larger than 99% for both processes of TaichuPix3 sensors. Detector efficiency The vertex detector beam test results show nearly identical results 98 95 94 The detection efficiency also to the sensor beam test. 5 GeV DUT can reach 99% for the vertex detector prototype at the Keterences lowest setting threshold [1] The CEPC Study Group, CEPC Conceptual Design Report: Volume 2 - Physics Detector (11 2018). doi:https://doi.org/10.48550/arXiv. 1811.10545. W. Sneeys, et al., A process modification for CMOS monolithic active pixel sensors for enhanced depletion, timing performance and radiation tolerance, Nucl. Instrum. Meth. A 871 (2017) 90–96. doi:http://dx.doi.org/10. 1016/j.nima.2017.07.046
V. Blobel, Software alignment for tracking detectors, Nuclear Instruments and Methods in Physics Research Section A: Accelerators, Spectrometers, Detectors and Associated Equipment 566 (1) (2006) 5–13, tiME 2005. doi:http://doi.org/10.1016/j.nima.2006.05.157. > Unbiased residual width Straight line fit The unbiased residual width [4] Kleinwort C (2012) General broken lines as advanced track fitting method. Nucl Instr Meth Phys Res A 673:107–110 [5] R. Diener, J. Dreyling-Eschweiler, H. Ehrlichmann, I. Gregor, U. Kötz, U. Krämer, N. Meyners, N. Potylitsina-Kube, A. Schütz, P. Schütze, M. Stanitzki, The DESY II test beam facility, Nucl. Instrum. Meth. A 922 (2019) 265–286. doi:https://doi.org/10.1016/j.nima.2018.11.133 before and after correction for multiple scattering [6] Jansen, H., Spannagel, S., Behr, J. et al. Performance of the EUDET-type beam telescopes. EPJ Techn Instrum 3, 7 (2016). https://doi.org/10.1140/epjti/s40485-016-0033-2